

TECHNICAL DATA SHEET

Drei Bond 1370

Revision: 15.06.2022

Version: 1.005



PRODUCT PROPERTIES

DB 1370 adhesive is a single-component anaerobic adhesive designed for securing, sealing and fastening threaded connections and form-fit connections.

It's particularly recommended for securing coaxial components such as bearings, sleeves and shaft-hubs.

This product features very good chemical and temperature resistance as well as extremely high strength.

PHYSICAL PROPERTIES

Appearance	liquid
Colour	red
Viscosity at 25 °C	18.000 – 20.000 mPa·s Brookfield (thixotropic) (25°C, spindle 2/30 RpM)
Specific weight DIN EN 542	1,1 g/ cm ³
Gap filling	M25 – 0,25 mm

CURING PROPERTIES

Handling cure time:	5 – 10 minutes
Functional cure time:	2 – 3 h
Full cure time:	4 – 12 h

Curing rate depends on the gap, assembly clearance, material surfaces and temperature. The use of Drei Bond activator speeds up the curing process.

PROPERTIES IN THE CURED STATE

Temperature range:	-60 °C to +220 °C
Shear strength (ISO 15337)	30 – 35 N/mm ²
Locking torque, breakaway (ISO 15865)	25 – 50 Nm

CHEMICAL RESISTANCE

According to the document "Resistance of Drei Bond anaerobic products to liquids, gases and solids".

STORAGE

- 12 months at RT in unopened packaging.

PACKAGE UNITS

- For manual application 10ml, 50 ml, 250 ml
- For industrial use 1 l, 2 l

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DIRECTIONS FOR USE

- Contaminated surfaces should be mechanically cleaned and degreased using Drei Bond Cleaner 3200. The prepared surfaces should be dry.
- Apply a small amount of the adhesive to the thread surface at the joint.

When sealing threaded connections, apply the adhesive to the first three turns of the external thread, evenly over the entire circumference.

- When bonding blind threads, cover the internal thread.
- For form-fit connections, assemble with a rotating motion.
- For press-fit connections, apply the adhesive to both surfaces.
- After 1 minute, do not move the bonded components, as this may break the bonds being formed.
- Increased temperature and the use of an activator accelerate the curing process.
- Heating the bond above +100°C facilitates disassembly and removal of old adhesive residue.

Drei Bond 5930 or 5900 activator should be used in the following cases:

- bonding components at temperatures below +15°C,
- bonding passive components,
- when it is necessary to shorten the technical assembly time.

For automatic processing we recommend to use Drei Bond application systems from stand-by equipments to full automatic CNC-controlled dosing machines.

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